PRESS RELEASE

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FOR IMMEDIATE RELEASE
August 19, 2015

TechSearch International Analyzes CSP Market Growth: QFNs Remain "Work Horse" of the Industry

Driven by use in mobile products such as smartphones, CSPs continue to show growth. TechSearch International's latest CSP market forecast shows an 11% CAGR from 2014 to 2019. One of the categories with the strongest growth is the quad flat no-lead (QFN) package. QFNs remain the "work horse" of the industry with growth driven by conversion from other leaded packages as well as adoption in new applications. QFNs are found in a wide range of products from automotive and industrial applications to wearable electronics. Increased use of QFNs for power devices continues to drive growth. New versions of the package are being introduced with routable QFNs gaining in popularity as a higher density solution that can support multiple die.

The analysis is provided in the latest Advanced Packaging Update, a 63-page report with full references and an accompanying set of 50 PowerPoint slides. The report also examines trends in stacked die CSPs and package-on-package (PoP) with a market forecast for each. A five-year market forecast for BGAs is provided. Drivers for each application space provide a clear picture of demand for each package type. A special section features thin wafer singulation, including the latest developments in plasma dicing.

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